ALICE Upgrades

The second second

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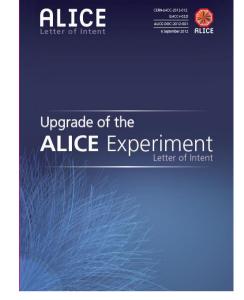
Motivation

- ALICE physics goals for Run 3
 - open HF hadrons, quarkonia down to zero p_T

thermalization, hadronization, recombination, temperature evolution of the QGP

vector mesons and low-mass di-leptons

chiral symmetry restoration, virtual thermal photons from the QGP



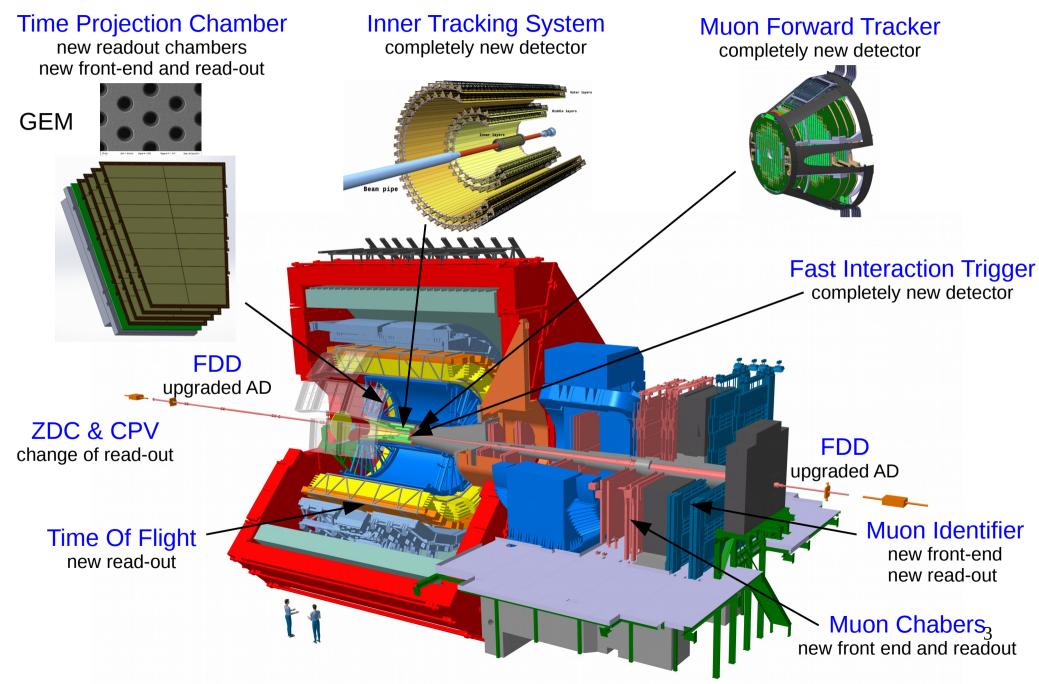
ALICE Lol, J.Phys. G41 (2014) 087001

- high-precision measurement of light (anti-)nuclei and hyper-nuclei nucleosynthesis, exotics
- Increase of delivered luminosity of Pb+Pb after LS2

 $L = 6 \times 10^{27} \text{ cm}^{-2} \text{ s}^{-1} \approx \text{ collision rate 50 kHz}$ (increase by factor 100)

Observables do not have suitable signatures for triggering \rightarrow Readout untriggered PbPb interactions at > 100 kHz

ALICE Upgrades in LS2

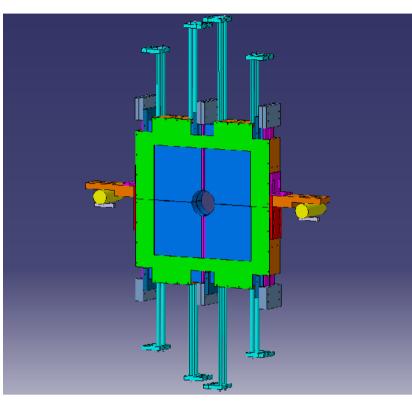


News from 2018

- FNSPE CTU will join Muon Forward Tracker (MFT) and plans to work also on Forward Diffractive Detector (FDD)
- Czech investment to MFT and FDD will be about 500 kCHF. Share between projects is a matter of negotiations.
- To be funded from the 2020-2022 budget (Run3 starts 2021)

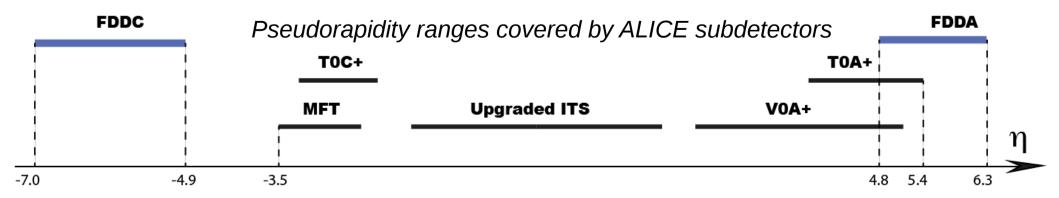
- NPI CAS continued in radation hardnes tests of silicon sensors for the upgraded Inner Tracking System
- Readout unit for the upgraded ITS passed sucessfully Production Readines Review in April

Forward Diffractive Detector



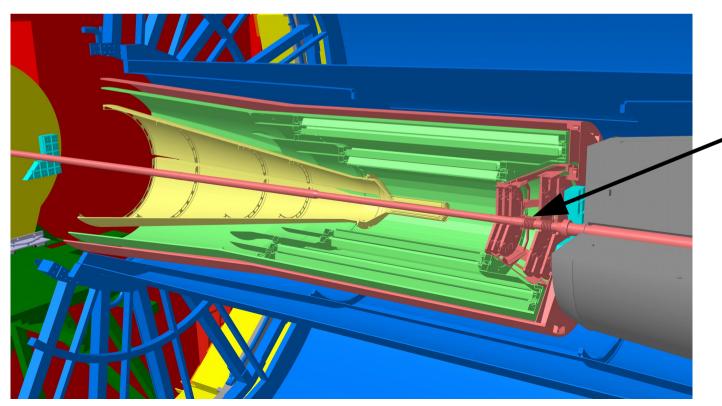
Total cost 250 kCHF

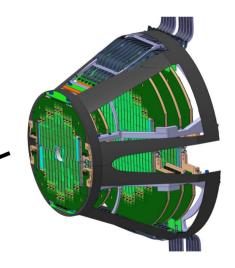
- Beam monitoring, luminometer, centrality, identification of diffractive processes
- Four modules of two plastic scintillators, read by wave-length shifters coupled to PMTs.
- Charge and time measurements.
- Expected time resolution below 0.5 ns
- Large dynamic range.
- Timeline: 2019-2020 construction,
 2020 installation and testing, 2021 physics
- FNSPE joins prototyping, testing, construction



Muon Forward Tracker

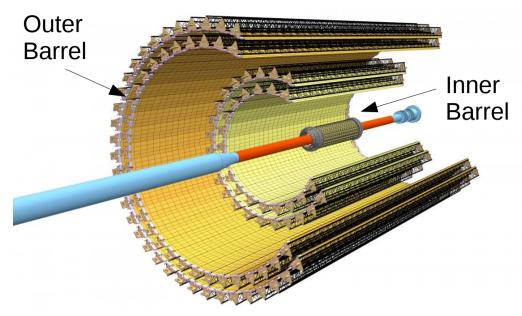
- Improves tracking resolution in front of the ALICE muon arm
- Open heavy flavor in single muon chanel, B from non prompt J/ψ , UPC
- FNSPE will participate in
 - testing and characterization of the readout
 - physics and development of the software in O_2



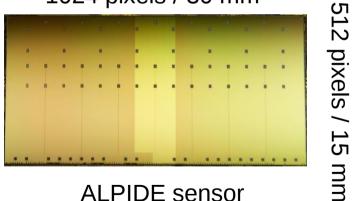


Total cost 3.3 MCHF Czech contribution will go to readout costs 6

Layout of the New ITS



1024 pixels / 30 mm



Number of layers7Range of radii23 - 400 mmPseudorapidity $|\eta| < 1.22$ Number of chips24000Number of pixels12.5 GArea 10 m^2

Monolitic Active Pixel Sensors ALPIDE = ALICE PIxel DEtector 180 nm CMOS imaging process by TowerJazz 3 cm x 1.5 cm x 50_{IB} / 100_{OB} µm Power consuption < 40 mW cm⁻²

Radiation load for the Inner Barrel TID 270 krad NIEL 10¹² 1MeVn_{eq} cm⁻² proposal requires an additional safety factor of 10

7

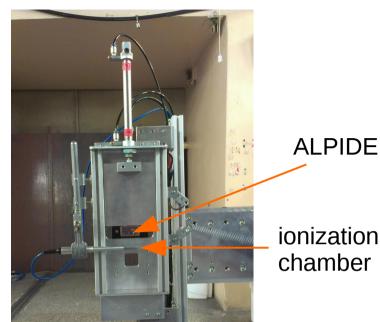
Total cost Czech contribution Faster ITS readout 13.6 MCHF257 kCHF (1.9%) payed in 2016230 kCHF payed in 2018 (addendum to the MoU)

Tests of radiation hardness for ITS at NPI

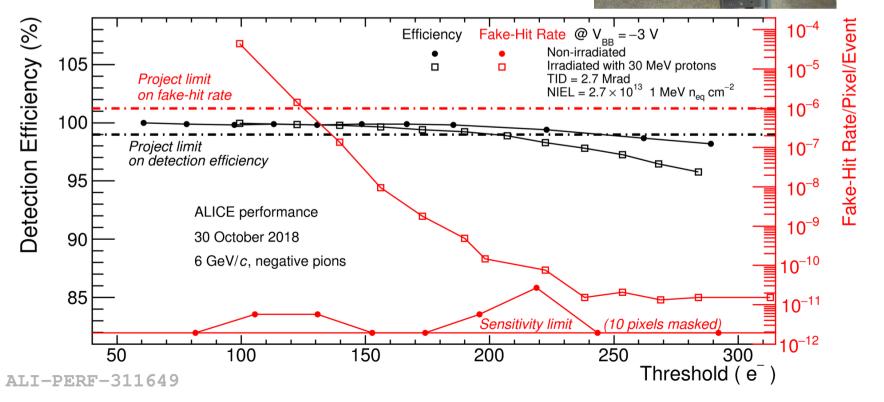
- 30 MeV protons from the NPI cyclotron
- Long term irradiation of ALPIDE sensor is finished (in 3 years the sensor obtained 2.7 Mrad TID and 2.7×10^{13} 1 MeV n_{eq} cm⁻² NIEL exceeding more than

10× the expected radiation load for the inner barrel)

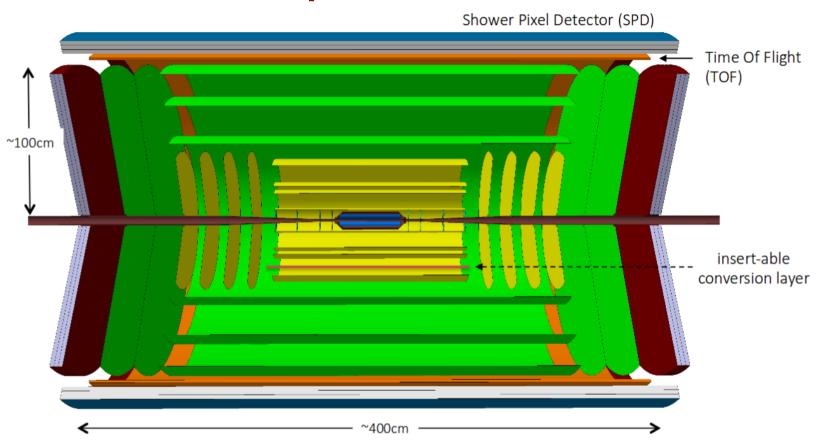
- ALPIDE fulfils radiation hardness requirements defined by the project technical design report!



ionization chamber



A next-generation LHC heavy-ion experiment

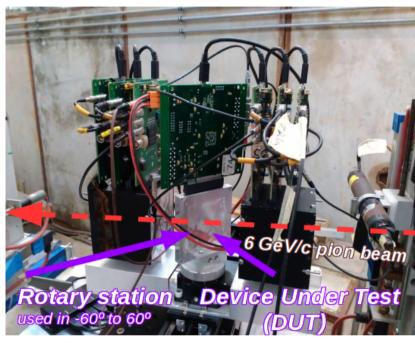


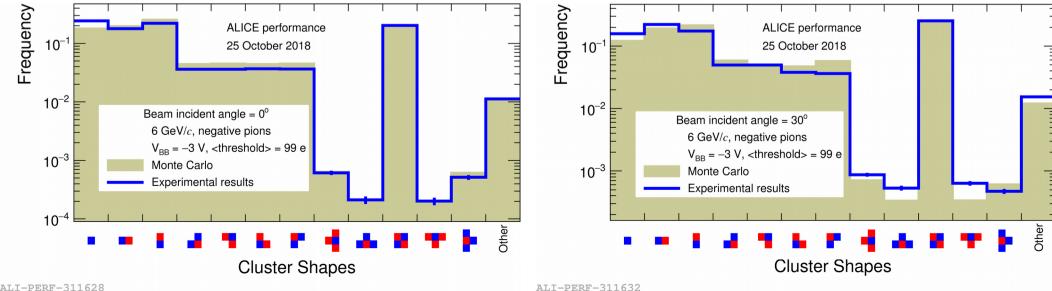
Proposed to replace ALICE in 2030 during LS4 (proposal for Open Symposium in Granada) Heavy flavor measurements down to $p_T 10 \text{ MeV/c}$, low mass dileptons, thermal QGP radiation Silicon tracker based on MAPS (IB placed in beam pipe $0.05\% X_0$ /layer, OB $0.5\% X_0$ /layer) Time of flight (CMOS Single Photon Avalanche Diodes, ~20 ps resolution) 9 Shower Pixel Detector to identify electrons and gammas

Backups

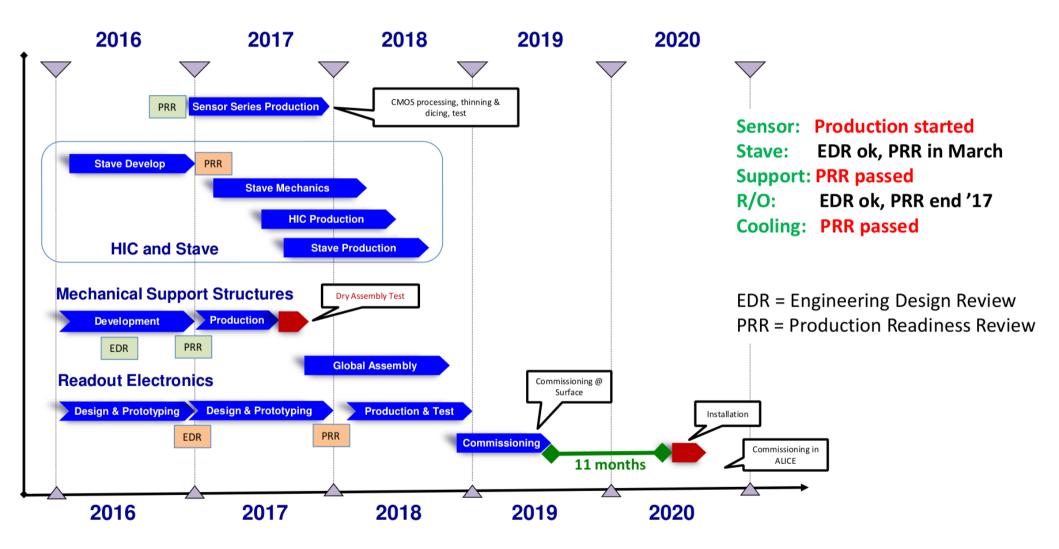
Characterization of ALPIDE response with inclined tracks and comparison to MC

- CERN PS 6 GeV/c pion beam
- Telescope of 7 ALPIDE planes, the ALPIDE in the middle is Device Under Test
- Simulation calculates drift and diffusion of charge in epitaxial layer and substrate volume and accounts for carrier lifetime [M.Suljic, CERN-THESIS-2017-304]

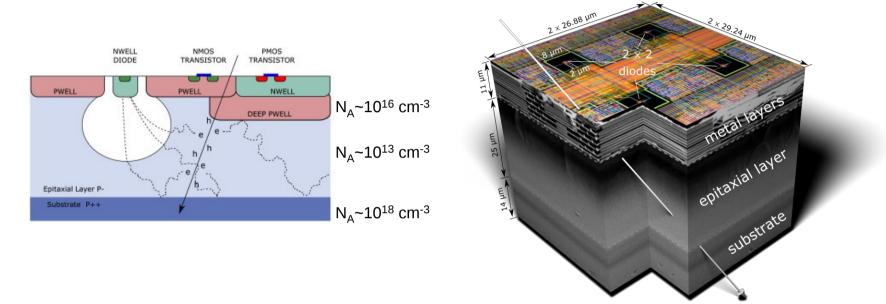




Time plan



ALPIDE Technology and Pixel Layout



- CMOS Pixel sensor using 180 nm CMOS Imaging Process by TowerJazz
- High-resistivity (> $1k\Omega$ cm) p-type epitaxial layer (25 µm) on p-type substrate
- Small n-well diode (2 μ m diameter), ~100 times smaller than pixel \rightarrow low capacitance (~fF)
- Deep PWELL shields NWELL of PMOS transistor
- Reverse bias to -6 V < V_{BB} < 0 V substrate
- Full CMOS circuitry within active area (amplification, discrimination, 3-hit register)